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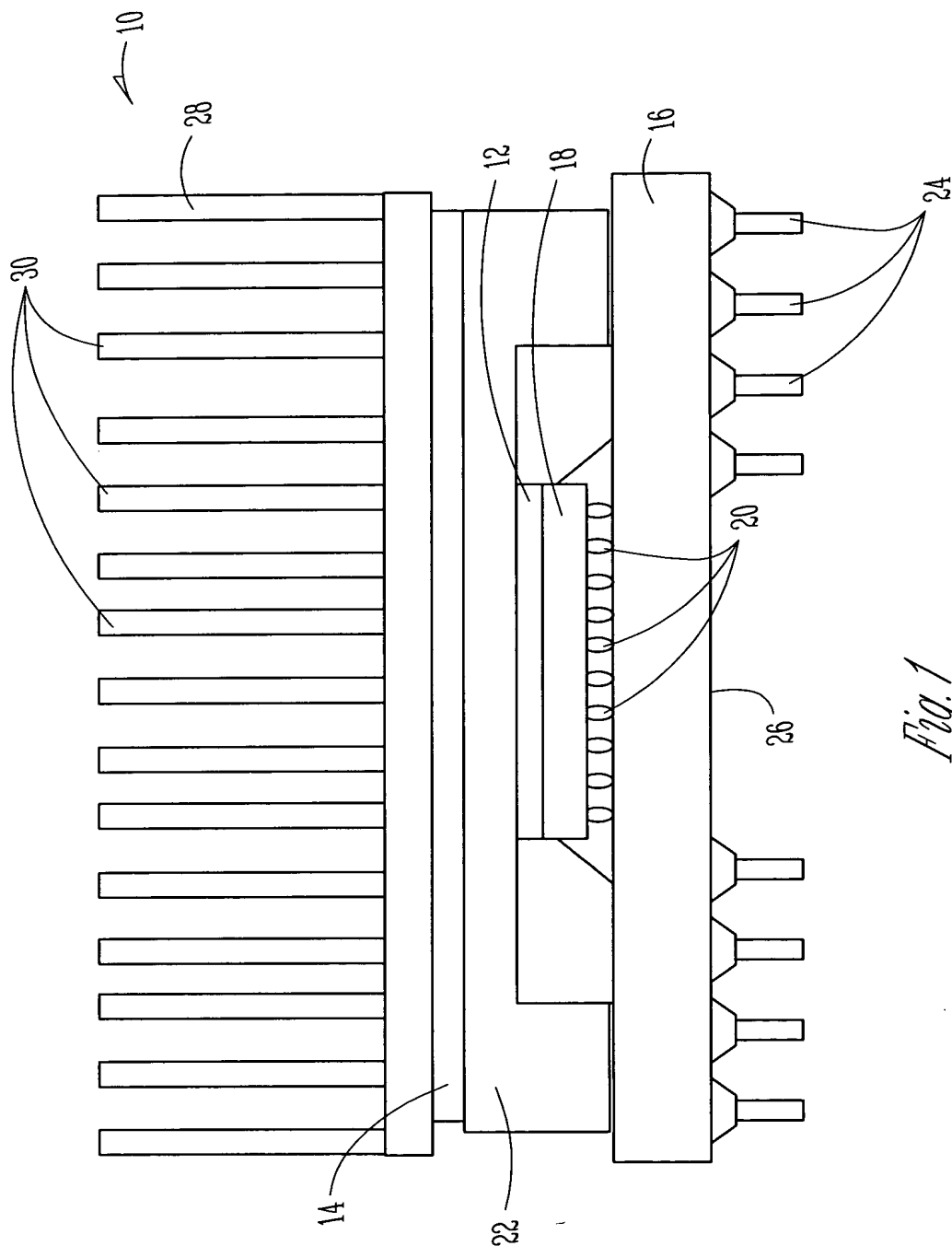


Fig. 1

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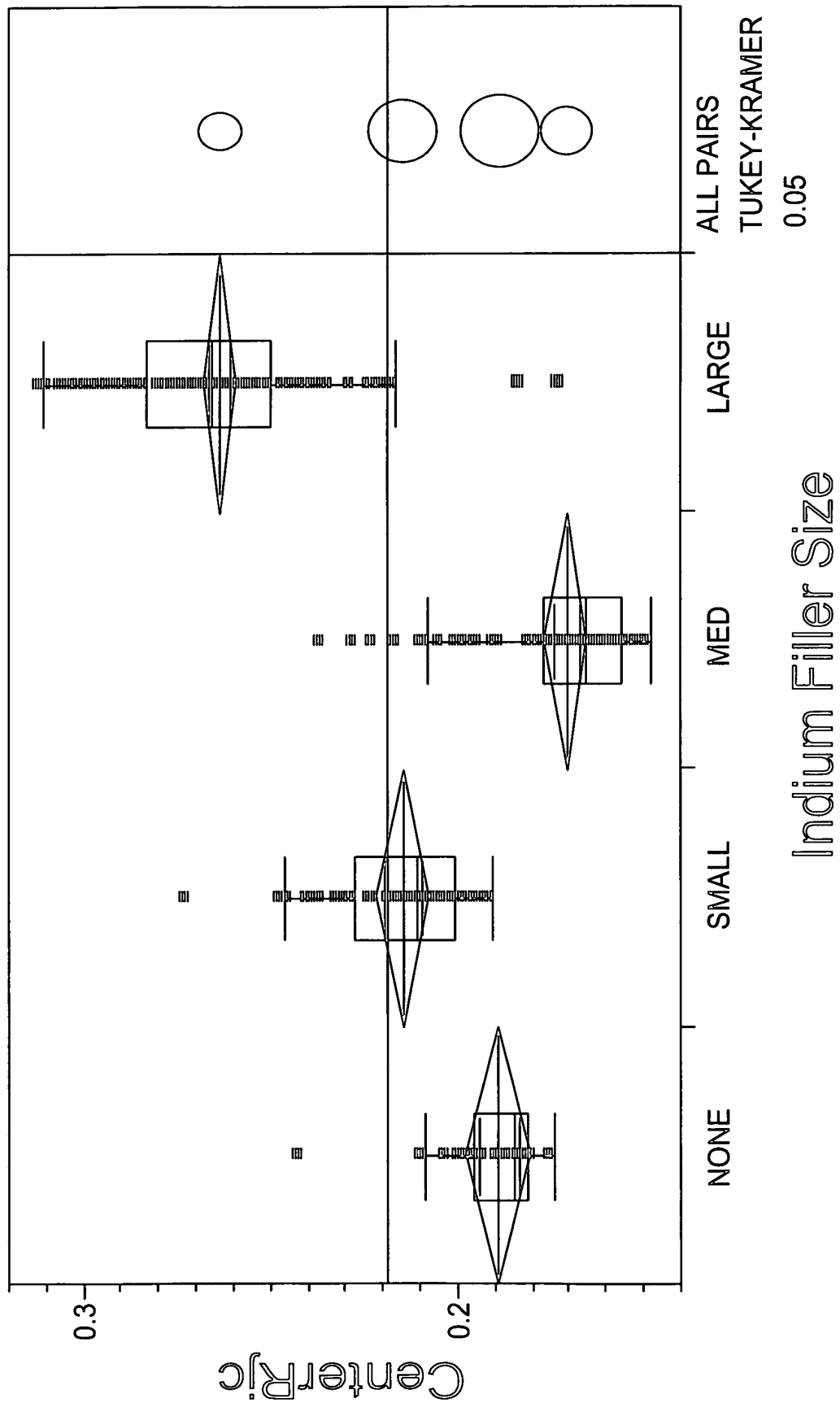
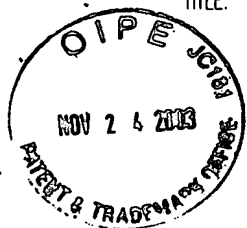
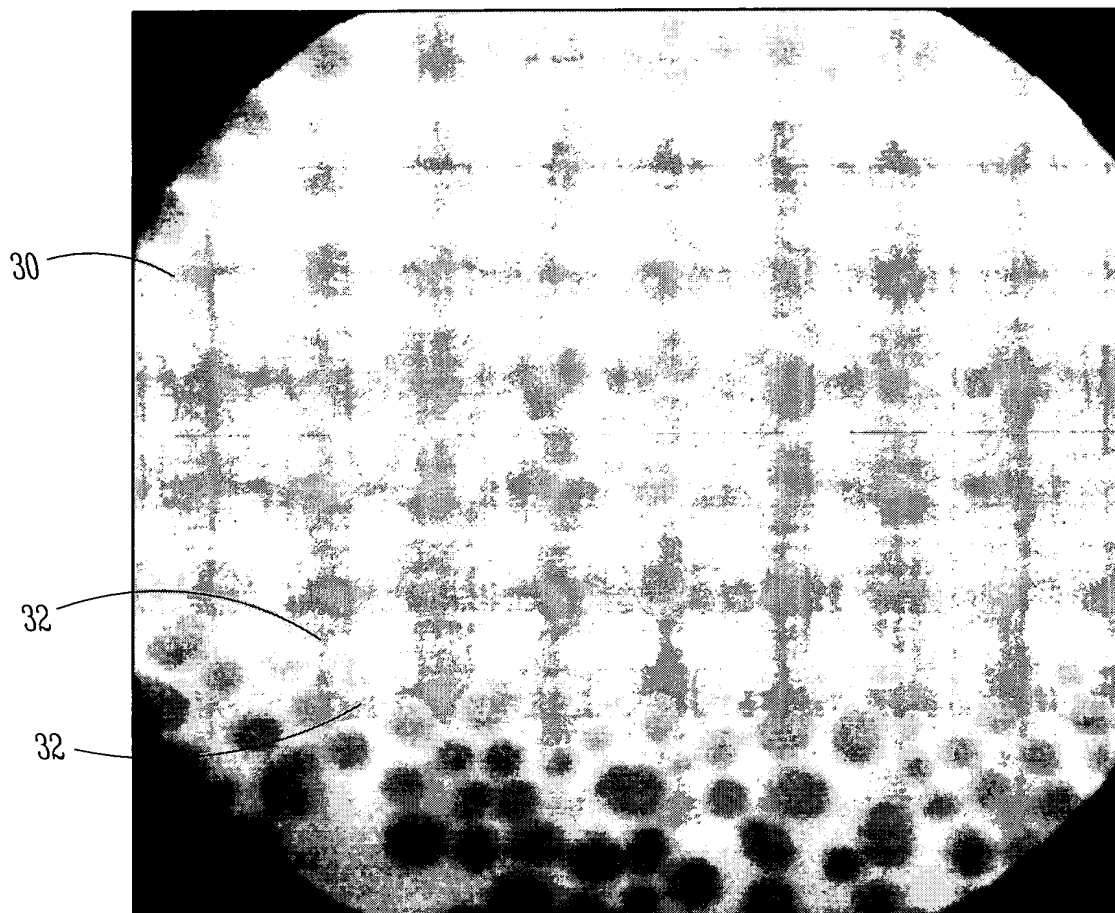


Fig. 2



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*Fig. 3*

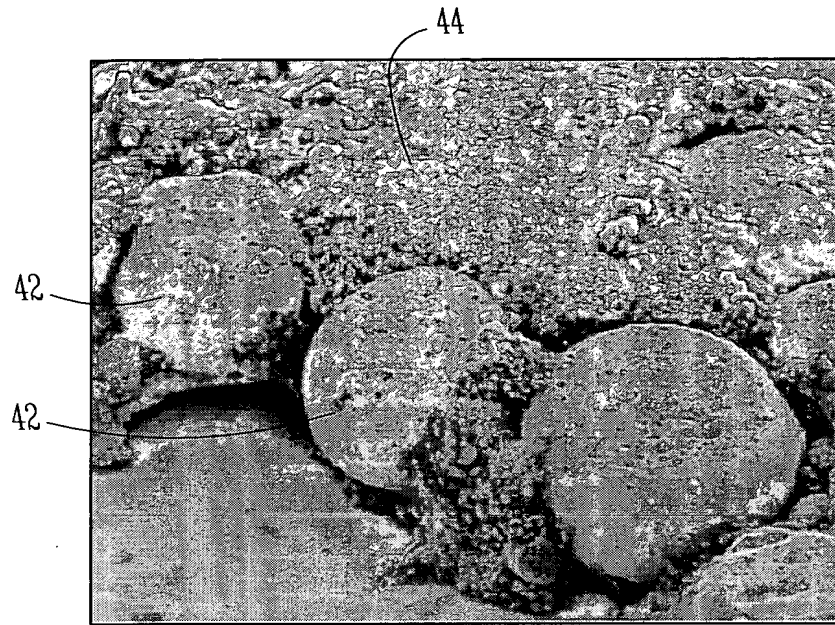


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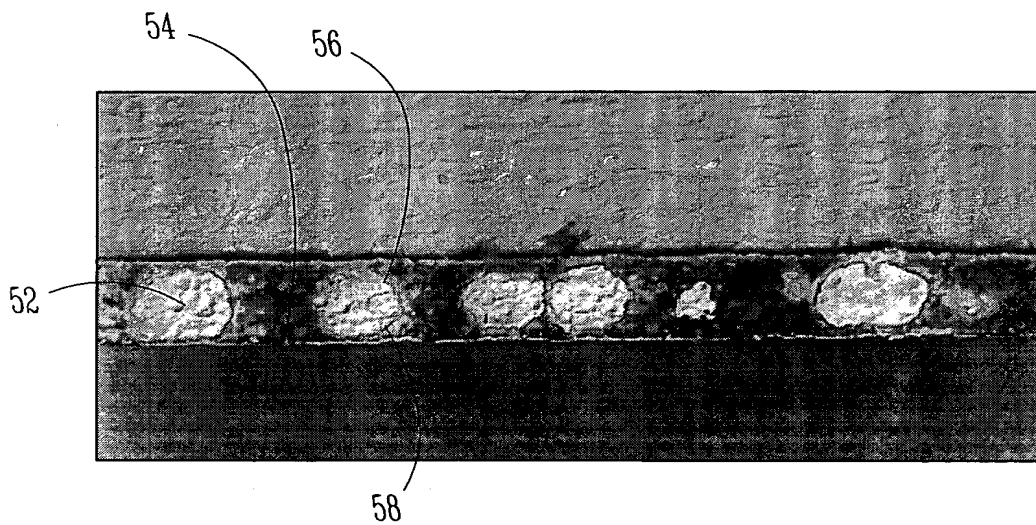
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*Fig. 4*



*Fig. 5*